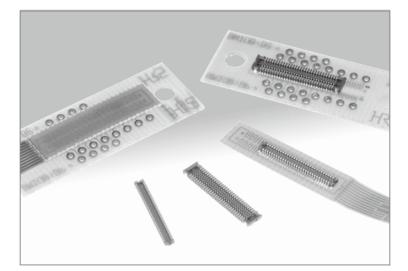
0.4 mm Contact Pitch, Stacking Height 0.6mm 0.8mm Board-to-Board /Board-to-FPC Connectors

BM10 Series



Features

1.Higher density of the board-mounted components

Extremely small board mounting pattern and low above heboard profile makes the connectors ideally suited for small device applications.

Globally unrivalled compact depth:when mated 2.98mm Header 2.46mm

Length - world's smallest class:10.4mm

2. Reliable electrical and mechanical connection

Despite its small mated height, unique contact configuration, with a 2-point contacts and effective mating length of 0.2mm(height 0.8mm)and 0.1mm(height 0.6mm), assures highly reliable connection while confirming a complete mating with a definite tactile feel.

3.Large self-alignment distance

The connectors will self-align within 0.3 mm.

4. Built-in shock absorbing feature

The protrusions and indents in the insulator bodies protect the connectors from failures when exposed to sudden impact.

5.Solder wicking prevention

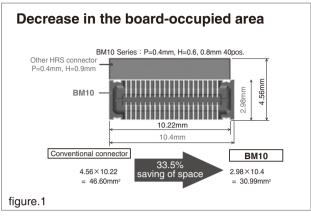
Nickel barriers prevent un-intentional solder wicking.

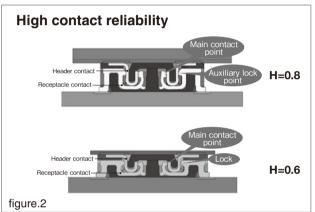
6.Contamination protection

Insulator walls protect the contact areas against flux splatter or other physical particles contamination.

7.Conducive traces on the PCB can run under the connector

No exposed contacts on the bottom of the connector.





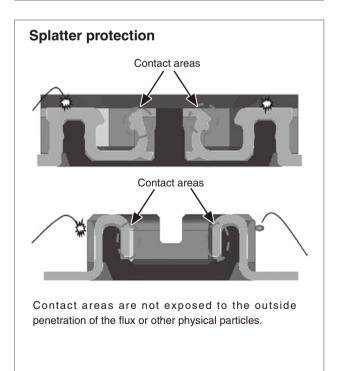


figure.3

∎S	nec	ific	atio	ne
B 3	μει	IIIC	auv	115

Potingo	Current rating	0.3 A	Operating temperature range	-35°C	to +85°C (Note 1)	Storage temperature range	-10°C to +60°C (Note 2)	
Ratings	Voltage rating	30 V AC, DC	Operating humidity range	RH 2	20% to 80%	Storage humidity range	RH 40% to 70% (Note 2)	
Item		Specification			Conditions			
1.Insulation resistance	500 MΩ min				100 V DC			
2.Withstanding voltage	No flashover	or insulation brea	kdown		100 V AC / 1m	inute		
3.Contact resistance	100 mΩ max.	100 mΩ max.			20 mV AC, 1 kHz, 1 mA			
4.Vibration	No electrical discontinuity of 1 μ s or longer No damage or parts dislocation			Frequency: 10 to 55 Hz, 5 min, single amplitude of 0.7 mm, 10 cycles, for each directions.				
5.Humidity		Contact resistance: 100 mΩ max., Insulation resistance: 25 MΩ min.		96 hours at 40 $\pm 2^\circ\text{C}$ and humidity of 90 to 95% No damage or parts dislocation				
6.Temperature cycle	Contact resistance: 100 m Ω max., Insulation resistance: 50 M Ω min. No damage or parts dislocation		min. Time: 30 min. \rightarrow 10 min. \rightarrow 30 min. \rightarrow 10 min.					
7.Durability	Contact resistance: 100 mΩ max.			10 cycles				
8.Resistance to soldering heat	No deformation of components affecting performance		ance Reflow: At the recommended temperature pro Manual soldering: 350°C for 3 seconds					

Note 1: Includes temperature rise caused by current flow.

Note 2: The term "storage" here refers to products stored for a long period prior to board mounting and use.

The operating temperature and humidity range covers the non-conducting condition of connectors after board mounting and the temporary storage conditions of transportation, etc.

Note 3: Information contained in this catalog represents general requirements for this Series. Contact us for the drawings and specifications for a specific part number shown.

Material

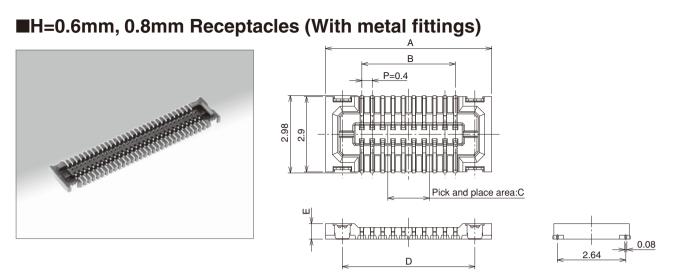
Product	Part	Material	Finish	Remarks
Receptacle	Insulator	LCP	Color:Black	UL94V-0
Header	Contacts	Phosphor bronze	Gold plated	

Ordering information

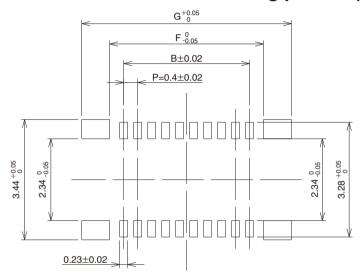
Receptacles / Headers

$$\frac{BM}{0} \quad \frac{10}{2} \quad \frac{\#}{6} \quad \frac{(**)}{0} \quad - \quad \frac{*}{6} \quad \frac{DS}{0} \quad - \quad \frac{0.4}{7} \quad \frac{V}{6} \quad \frac{(**)}{9}$$

Series name : BMSeries No.: 10	Connector style DS:Double-row receptacle
 Configuration B:With mettal fittings NB:With mettal fittings J:Connector for conductivity tests 	DP:Double-row header Contact pitch : 0.4mm Termination type VSMT vertical mount
Stacking Height 0.6mm, 0.8mmNumber of contacts.10 to 60	 Packaging (51): Embossed tape packaging (8,000 pieces per reel) (53): Embossed tape packaging (1,000 pieces per reel)



■Recommended PCB mounting pattern (H=0.6mm,0.8mm)

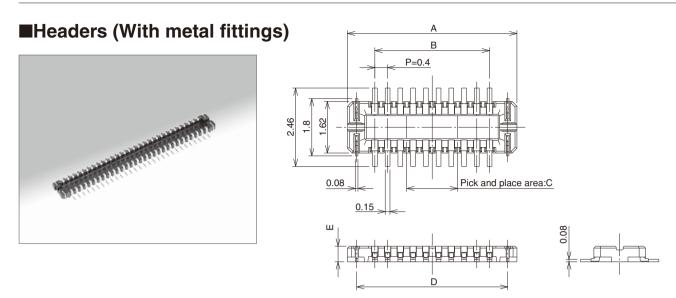


Part Number	CL No.	Number of Contacts	А	В	С	D	E	F	G
BM10NB(0.6)-10DS-0.4V(51)	684-6305-3-51	10	4.4	1.6	0.8	3.1	0.6	2.18	4.02
BM10NB(0.6)-20DS-0.4V(51)	684-6314-4-51	20	6.4	3.6	1.6	5.1	0.6	4.18	6.02
BM10NB(0.6)-24DS-0.4V(51)	684-6303-8-51	24	7.2	4.4	2	5.9	0.6	4.98	6.82
BM10NB(0.6)-30DS-0.4V(51)	684-6315-7-51	30	8.4	5.6	2	7.1	0.6	6.18	8.02
BM10NB(0.6)-34DS-0.4V(51)	Under development	34	9.2	6.4	2.4	7.9	0.6	6.98	8.82
BM10NB(0.6)-40DS-0.4V(51)	684-6317-2-51	40	10.4	7.6	2.4	9.1	0.6	8.18	10.02
BM10NB(0.6)-50DS-0.4V(51)	684-6319-8-51	50	12.4	9.6	2.8	11.1	0.6	10.18	12.02
BM10NB(0.6)-60DS-0.4V(51)	684-6301-2-51	60	14.4	11.6	3.2	13.1	0.6	12.18	14.02
							А	II dimens	ions: mm
Part Number	CL No.	Number of Contacts	А	В	С	D	E	F	G
BM10NB(0.8)-10DS-0.4V(51)	684-6100-0-51	10	4.4	1.6	0.8	3.1	0.8	2.18	4.02
BM10NB(0.8)-16DS-0.4V(51)	684-6110-4-51	16	5.6	2.8	1.6	4.3	0.6	3.38	5.22
BM10NB(0.8)-20DS-0.4V(51)	684-6105-4-51	20	6.4	3.6	1.6	5.1	0.8	4.18	6.02
BM10NB(0.8)-24DS-0.4V(51)	684-6101-3-51	24	7.2	4.4	2	5.9	0.8	4.98	6.82
BM10NB(0.8)-30DS-0.4V(51)	684-6106-7-51	30	8.4	5.6	2	7.1	0.8	6.18	8.02
BM10NB(0.8)-34DS-0.4V(51)	684-6108-2-51	34	9.2	6.4	2.4	7.9	0.8	6.98	8.82
BM10NB(0.8)-40DS-0.4V(51)	684-6107-0-51	40	10.4	7.6	2.4	9.1	0.8	8.18	10.02
BM10NB(0.8)-44DS-0.4V(51)	684-6109-5-51	44	11.2	8.4	2.8	9.9	0.8	8.98	10.82
BM10NB(0.8)-50DS-0.4V(51)	684-6102-6-51	50	12.4	9.6	2.8	11.1	0.8	10.18	12.02
BM10NB(0.8)-60DS-0.4V(51)	684-6103-9-51	60	14.4	11.6	3.2	13.1	0.8	12.18	14.02

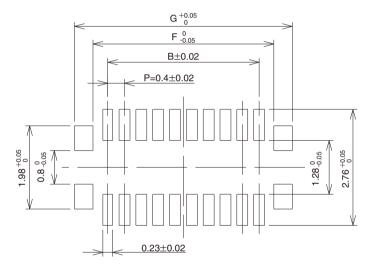
Note 1 : Order by number of reels.

Note 2 : This connector is NOT polarized.

All dimensions: mm



Recommended metal mask dimensions



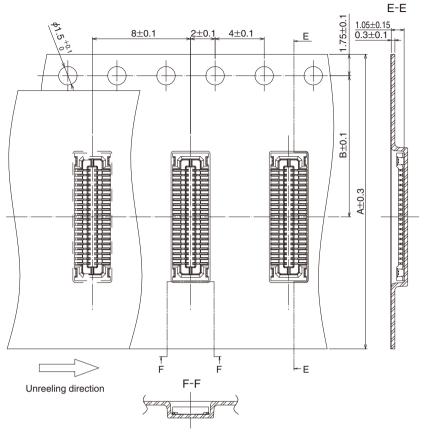
							A	II dimens	ions: mm
Part Number	CL No.	Number of Contacts	А	В	С	D	Е	F	G
BM10B(0.6)-10DP-0.4V(51)	684-6304-0-51	10	3.32	1.6	0.8	2.74	0.49	2.3	3.18
BM10B(0.6)-20DP-0.4V(51)	684-6313-1-51	20	5.32	3.6	1.6	4.74	0.49	4.3	5.18
BM10B(0.6)-24DP-0.4V(51)	684-6302-5-51	24	6.12	4.4	2	5.54	0.49	5.1	5.98
BM10B(0.6)-30DP-0.4V(51)	684-6307-9-51	30	7.32	5.6	2	6.74	0.49	6.3	7.18
BM10B(0.6)-34DP-0.4V(51)	Under development	34	8.12	6.4	2.4	7.54	0.49	7.1	7.98
BM10B(0.6)-40DP-0.4V(51)	684-6316-0-51	40	9.32	7.6	2.4	8.74	0.49	8.3	9.18
BM10B(0.6)-50DP-0.4V(51)	684-6309-4-51	50	11.32	9.6	2.8	10.74	0.49	10.3	11.18
BM10B(0.6)-60DP-0.4V(51)	684-6300-0-51	60	13.32	11.6	3.2	12.74	0.49	12.3	13.18
							А	II dimens	ions: mm
Part Number	CL No.	Number of Contacts	А	В	С	D	Е	F	G
BM10B(0.8)-10DP-0.4V(51)	684-6007-5-51	10	3.32	1.6	0.8	2.74	0.63	2.3	3.18
BM10B(0.8)-16DP-0.4V(51)	684-6047-0-51	16	4.52	2.8	1.6	3.94	0.63	3.5	4.38
BM10B(0.8)-20DP-0.4V(51)	684-6009-0-51	20	5.32	3.6	1.6	4.74	0.63	4.3	5.18
BM10B(0.8)-24DP-0.4V(51)	684-6011-2-51	24	6.12	4.4	2	5.54	0.63	5.1	5.98
BM10B(0.8)-30DP-0.4V(51)	684-6013-8-51	30	7.32	5.6	2	6.74	0.63	6.3	7.18
BM10B(0.8)-34DP-0.4V(51)	684-6015-3-51	34	8.12	6.4	2.4	7.54	0.63	7.1	7.98
BM10B(0.8)-40DP-0.4V(51)	684-6003-4-51	40	9.32	7.6	2.4	8.74	0.63	8.3	9.18
BM10B(0.8)-44DP-0.4V(51)	684-6039-1-51	44	10.12	8.4	2.8	9.54	0.63	9.1	9.98
BM10B(0.8)-50DP-0.4V(51)	684-6017-9-51	50	11.32	9.6	2.8	10.74	0.63	10.3	11.18
BM10B(0.8)-60DP-0.4V(51)	684-6001-9-51	60	13.32	11.6	3.2	12.74	0.63	12.3	13.18

Note 1 : Order by number of reels.

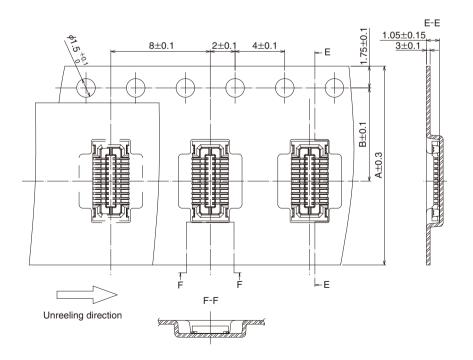
Note 2 : This connector is NOT polarized.

■Embossed Carrier Tape Dimensions (H=0.6mm,0.8mm)

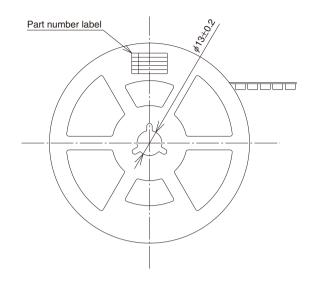
•Receptacle (24 and above positions)

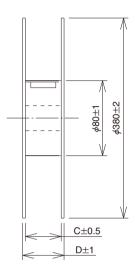


•Receptacle (less than 24 positions)



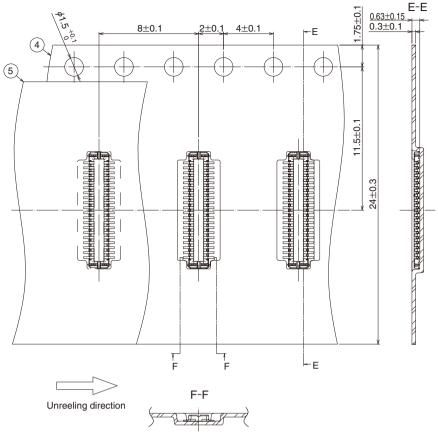
■Reel dimensions (Receptacles)



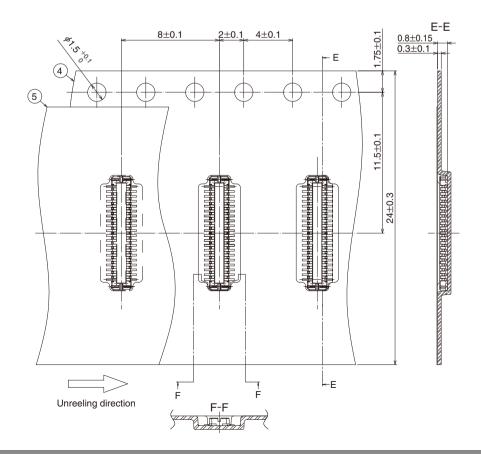


				Unit : mm
Part Number	A	В	С	D
BM10#(**)-10DS-0.4V(51)	16	7.5	17.5	21.5
BM10#(**)-16DS-0.4V(51)	16	7.5	17.5	21.5
BM10#(**)-20DS-0.4V(51)	16	7.5	17.5	21.5
BM10#(**)-24DS-0.4V(51)	16	7.5	17.5	21.5
BM10#(**)-30DS-0.4V(51)	24	11.5	25.5	29.5
BM10#(**)-34DS-0.4V(51)	24	11.5	25.5	29.5
BM10#(**)-40DS-0.4V(51)	24	11.5	25.5	29.5
BM10#(**)-44DS-0.4V(51)	24	11.5	25.5	29.5
BM10#(**)-50DS-0.4V(51)	24	11.5	25.5	29.5
BM10#(**)-60DS-0.4V(51)	24	11.5	25.5	29.5

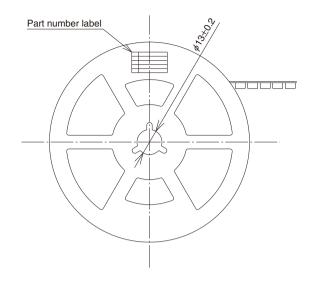


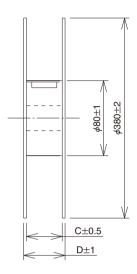


●H=0.8mm header



■Reel dimensions (Header)



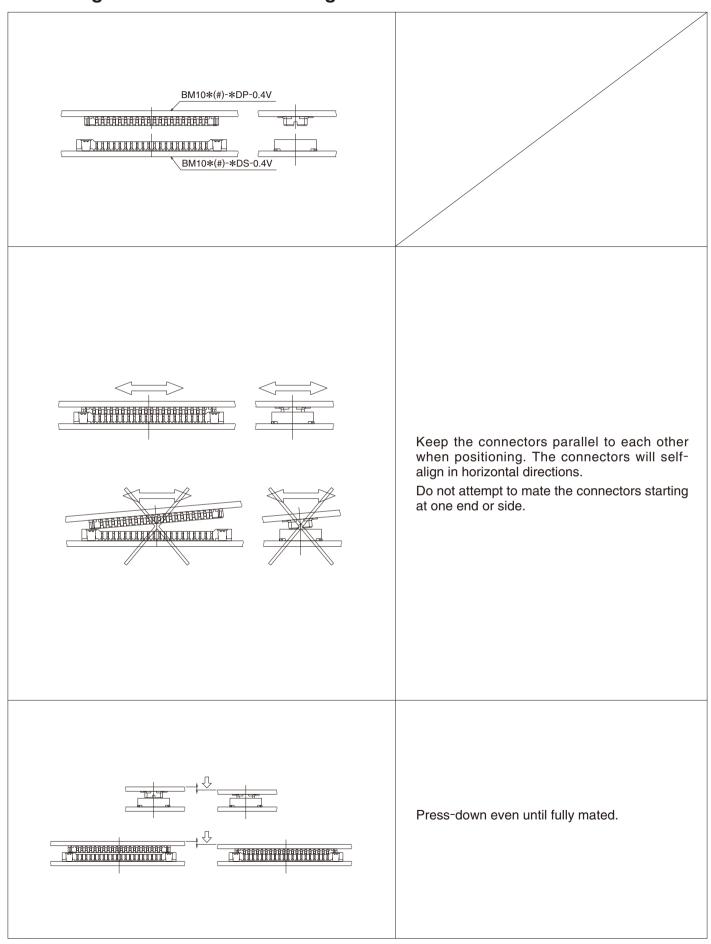


				Unit : mm
Part Number	A	В	С	D
BM10#(**)-10DP-0.4V(51)	12	5.5	13.5	17.5
BM10#(**)-16DP-0.4V(51)	16	7.5	17.5	21.5
BM10#(**)-20DP-0.4V(51)	16	7.5	17.5	21.5
BM10#(**)-24DP-0.4V(51)	16	7.5	17.5	21.5
BM10#(**)-30DP-0.4V(51)	16	7.5	17.5	21.5
BM10#(**)-34DP-0.4V(51)	16	7.5	17.5	21.5
BM10#(**)-40DP-0.4V(51)	24	11.5	25.5	29.5
BM10#(**)-44DP-0.4V(51)	24	11.5	25.5	29.5
BM10#(**)-50DP-0.4V(51)	24	11.5	25.5	29.5
BM10#(**)-60DP-0.4V(51)	24	11.5	25.5	29.5

■Usage Recommendations

1.Recommended temperature profile	
	Temperature (°C)
	250
	220°C
	200 [60sec max]
	150 - 150°C -
	90~120sec
	S0 -/
	0 50 100 150 200 250 300
	Time (sec.)
	Note 1: Up to 2 cycles of Reflow soldering are possible under the
	same conditions, provided that there is a return to normal
	temperature between the first and second cycle.
	Note 2: The temperature profile indicates the board surface
	temperature at the point of contacts with the connector
	terminals.
2.Recommended manual soldering	Manual soldering: 340±10°C for 3 seconds
3.Recommended screen thickness and open	H=0.8mm Header, Receptacle :Thickness 0.12mm
area ratio (Pattern area ratio)	:Open area ratio 100%
	* When using nitrogen-reflow, 75% only at the header side.
	H=0.6mm Header Thickness 0.1mm
	H=0.6mm Header Thickness 0.1mm Receptacle 0.12mm:Open area ratio 100%
4 Board warnage	H=0.6mm Header Thickness 0.1mm Receptacle 0.12mm:Open area ratio 100% * When using nitrogen-reflow, 75% only at the header side.
4.Board warpage	H=0.6mm Header Thickness 0.1mm Receptacle 0.12mm:Open area ratio 100% * When using nitrogen-reflow, 75% only at the header side. Maximum of 0.02 mm at the connector center, with both ends of the
-	H=0.6mm Header Thickness 0.1mm Receptacle 0.12mm:Open area ratio 100% * When using nitrogen-reflow, 75% only at the header side. Maximum of 0.02 mm at the connector center, with both ends of the connector as reference points.
4.Board warpage 5.Cleaning conditions 6.Precautions	H=0.6mm Header Thickness 0.1mm Receptacle 0.12mm:Open area ratio 100% * When using nitrogen-reflow, 75% only at the header side. Maximum of 0.02 mm at the connector center, with both ends of the connector as reference points. Refer to "Nylon Connector Use Handbook".
5.Cleaning conditions	H=0.6mm Header Thickness 0.1mm Receptacle 0.12mm:Open area ratio 100% * When using nitrogen-reflow, 75% only at the header side. Maximum of 0.02 mm at the connector center, with both ends of the connector as reference points.
5.Cleaning conditions	 H=0.6mm Header Thickness 0.1mm Receptacle 0.12mm:Open area ratio 100% ★ When using nitrogen-reflow, 75% only at the header side. Maximum of 0.02 mm at the connector center, with both ends of the connector as reference points. Refer to "Nylon Connector Use Handbook". ■ Mating and un-mating of the connectors when not soldered on the
5.Cleaning conditions	 H=0.6mm Header Thickness 0.1mm Receptacle 0.12mm:Open area ratio 100% * When using nitrogen-reflow, 75% only at the header side. Maximum of 0.02 mm at the connector center, with both ends of the connector as reference points. Refer to "Nylon Connector Use Handbook". I Mating and un-mating of the connectors when not soldered on the boards is not recommended as this may cause deformation of the
5.Cleaning conditions	 H=0.6mm Header Thickness 0.1mm Receptacle 0.12mm:Open area ratio 100% * When using nitrogen-reflow, 75% only at the header side. Maximum of 0.02 mm at the connector center, with both ends of the connector as reference points. Refer to "Nylon Connector Use Handbook". Mating and un-mating of the connectors when not soldered on the boards is not recommended as this may cause deformation of the terminals, damage to the contacts or insulators. Mated connectors should not carry weight of the board by themselves. Provide some other support of the boards.
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5.Cleaning conditions	 H=0.6mm Header Thickness 0.1mm Receptacle 0.12mm:Open area ratio 100% * When using nitrogen-reflow, 75% only at the header side. Maximum of 0.02 mm at the connector center, with both ends of the connector as reference points. Refer to "Nylon Connector Use Handbook". Mating and un-mating of the connectors when not soldered on the boards is not recommended as this may cause deformation of the terminals, damage to the contacts or insulators. Mated connectors should not carry weight of the board by themselves. Provide some other support of the boards. When mating/un-mating do not twist or lift by the corners. Apply the forces evenly across the entire length and width of the connectors
5.Cleaning conditions	 H=0.6mm Header Thickness 0.1mm Receptacle 0.12mm:Open area ratio 100% * When using nitrogen-reflow, 75% only at the header side. Maximum of 0.02 mm at the connector center, with both ends of the connector as reference points. Refer to "Nylon Connector Use Handbook". Mating and un-mating of the connectors when not soldered on the boards is not recommended as this may cause deformation of the terminals, damage to the contacts or insulators. Mated connectors should not carry weight of the board by themselves. Provide some other support of the boards. When mating/un-mating do not twist or lift by the corners. Apply the forces evenly across the entire length and width of the connectors taking care NOT to damage or deform soldered terminations.
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5.Cleaning conditions	 H=0.6mm Header Thickness 0.1mm Receptacle 0.12mm:Open area ratio 100% * When using nitrogen-reflow, 75% only at the header side. Maximum of 0.02 mm at the connector center, with both ends of the connector as reference points. Refer to "Nylon Connector Use Handbook". Mating and un-mating of the connectors when not soldered on the boards is not recommended as this may cause deformation of the terminals, damage to the contacts or insulators. Mated connectors should not carry weight of the board by themselves. Provide some other support of the boards. When mating/un-mating do not twist or lift by the corners. Apply the forces evenly across the entire length and width of the connectors taking care NOT to damage or deform soldered terminations. Exercise extreme caution when mating/ un-mating when the connector is mounted on a nonrigid (flexible) substrate.
5.Cleaning conditions	 H=0.6mm Header Thickness 0.1mm Receptacle 0.12mm:Open area ratio 100% * When using nitrogen-reflow, 75% only at the header side. Maximum of 0.02 mm at the connector center, with both ends of the connector as reference points. Refer to "Nylon Connector Use Handbook". Mating and un-mating of the connectors when not soldered on the boards is not recommended as this may cause deformation of the terminals, damage to the contacts or insulators. Mated connectors should not carry weight of the board by themselves. Provide some other support of the boards. When mating/un-mating do not twist or lift by the corners. Apply the forces evenly across the entire length and width of the connectors taking care NOT to damage or deform soldered terminations. Exercise extreme caution when mating/ un-mating when the connector is mounted on a nonrigid (flexible) substrate. Slight discoloration on the insulating materials will not affect form,
5.Cleaning conditions	 H=0.6mm Header Thickness 0.1mm Receptacle 0.12mm:Open area ratio 100% * When using nitrogen-reflow, 75% only at the header side. Maximum of 0.02 mm at the connector center, with both ends of the connector as reference points. Refer to "Nylon Connector Use Handbook". Mating and un-mating of the connectors when not soldered on the boards is not recommended as this may cause deformation of the terminals, damage to the contacts or insulators. Mated connectors should not carry weight of the board by themselves. Provide some other support of the boards. When mating/un-mating do not twist or lift by the corners. Apply the forces evenly across the entire length and width of the connectors taking care NOT to damage or deform soldered terminations. Exercise extreme caution when mating/ un-mating when the connector is mounted on a nonrigid (flexible) substrate.

■Handling Precautions when Mating Connectors



10 **RS**

CHandling Precautions When Un-mating Connectors

BM10*(#)-*DP-0.4V	Fully mated
	Lift even, keeping both connectors parallel to each other
Pitch orientation	 When handling, circumstances may prevent the connectors from being kept parallel when un-mating. One end may be lifted as shown. However, to use this procedure the connector must be mounted on sufficiently rigid circuit board. Any deflection of the board during this operation may result in damage to the connector or solder joints.
Corner orientation	Do not attempt to start the un-mating of the connectors from one side or corner. Failure to exercise caution when un-mating the connectors mounted on the non-rigid FPC may also result in connector breakage. It is the responsibility of the user to perform verification of the repeated mating / un-mating cycles with the connectors mounted on the applicable FPC.
	When the rigidity of the FPC is low, there is a risk that the connector could break as illustrated in the diagram at left. Please use the connectors after performing a check of repeated operation with the FPC that the customer will be using. Evaluative results of FPC rigidity and various items are available. Please inquire.